

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: **Sun, et al.** § Case: **AMAT/8241/CMP/ECP/RKK**  
Serial No.: **10/616,097** § Filed: **July 8, 2003**  
Examiner: **Edna Wong** § Group Art Unit: **1753**  
Confirmation No.: **1645** §  
Title: **MULTIPLE-STEP**  
**ELECTRODEPOSITION PROCESS**  
**FOR DIRECT COPPER PLATING ON**  
**BARRIER MATERIALS** §

MAIL STOP Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Do not enter. (3) 1/23/08  
Dear Sir:

**RESPONSE TO FINAL OFFICE ACTION DATED NOVEMBER 21, 2007**

In response to the Final Office Action dated November 21, 2007 having a shortened statutory period for response set to expire on February 21, 2008, please enter this response and reconsider the claims pending in the application for the reasons discussed below. Although the Applicants believe that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782 for any other fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.